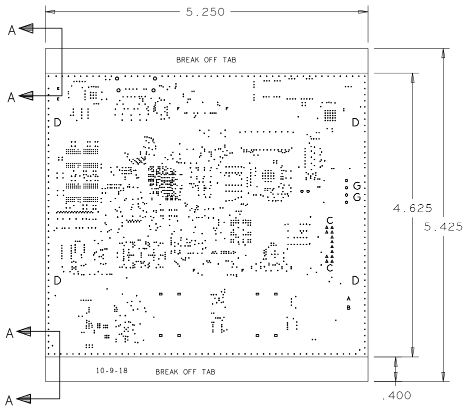
NOTES: UNLESS OTHERWISE SPECIFIED

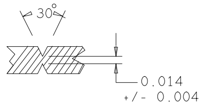
1. TOTAL BOARD THICKNESS SHALL BE .062 +/- .007 INCHES.
   ALL MATERIAL SHALL BE NEMA GRADE FR-4 OR EQUIVALENT, TG>=170C,
   FLAMMABILITY, 94V-0.
2. REFER TO STACKUP DRAWING FOR COPPER WEIGHT.
   AVERAGE COPPER ON THE WALL OF THE
   PLATED HOLE SHALL BE PER IPC CLASS 2.
3. MINIMUM CLEARANCE ON THE BOARD SHALL BE 4 MILS.
   MINIMUM TRACE WIDTH ON THE BOARD SHALL BE 4 MILS.
4. SOLDERMASK ON BOTH SIDES OF THE BOARD SHALL BE S.M.O.B.C., LPI, COLOR GREEN.
5. PLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .003 INCH.
   UNPLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .002 INCH.
6. DRC'S MUST BE RUN ON THE GERBERS BEFORE BUILDING BOARDS UNLESS PRIOR
   APPROVAL IS GIVEN IN WRITING.
7. FINISHED BOARD SHALL BE FREE OF BURRS ON EDGES.
8. SURFACE FINISH SHALL BE IMMERSION GOLD.
9. ENVIRONMENTAL COMPLIANCE:
   LEAD (PB)-FREE, ROHS, AND REACH COMPLIANT WITHOUT EXEMPTIONS.
10. IMPEDANCE CONTROL:
   REFER TO STACKUP DRAWING FOR IMPEDANCE CONTROL.

DRILL CHART					
ALL UNITS ARE IN MILS					
FIGURE	SIZE	PLATED	QTY	TOL	NOTE
·	8.0	PLATED	183		
·	8.0	PLATED	102		
·	8.0	PLATED	185		
·	10.0	PLATED	1468		
·	12.0	PLATED	6		
·	13.0	PLATED	10		
▲	39.0	PLATED	12		
○	40.0	PLATED	2		
D	41.0	PLATED	4		
□	41.3	PLATED	8		
O	51.0	PLATED	4		
A	55.0	PLATED	1		
B	55.0	PLATED	1		
C	100.0	PLATED	2		
D	125.0	PLATED	4		
E	35.0	NON-PLATED	2		
F	40.0	NON-PLATED	4		
G	118.0	NON-PLATED	2		



	TEXAS INSTRUMENTS
	TIDEP-01002
	DATE: 10-11-18

TSLK
SMC
LAYER 1
LAYER 2
LAYER 3
LAYER 4
LAYER 5
LAYER 6
SMS
BSLK



VIEW A - A
SCALE: NONE

LAYER SCHEDULE

SCALE: NONE

	APPROVED		TEXAS INSTRUMENTS
	CHECKED		
	DRAFTING	SD	
DATE 10-11-18	ENGR		FABRICATION DRAWING, DCARD CPU BOARD
DESIGN ENGR	TOLERANCES UNLESS OTHERWISE SPECIFIED X.XX ± 0.01 X.XXX ± 0.005 ANGLES ± 1/2°		
PROJECT ENGR			
ENGR MGR			SCALE NONE SHEET 1 OF 1
NEXT ASSEMBLY	DO NOT SCALE DRAWING		TIDEP-01002 SIZE D

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